

MMA034AA Bonding Diagram

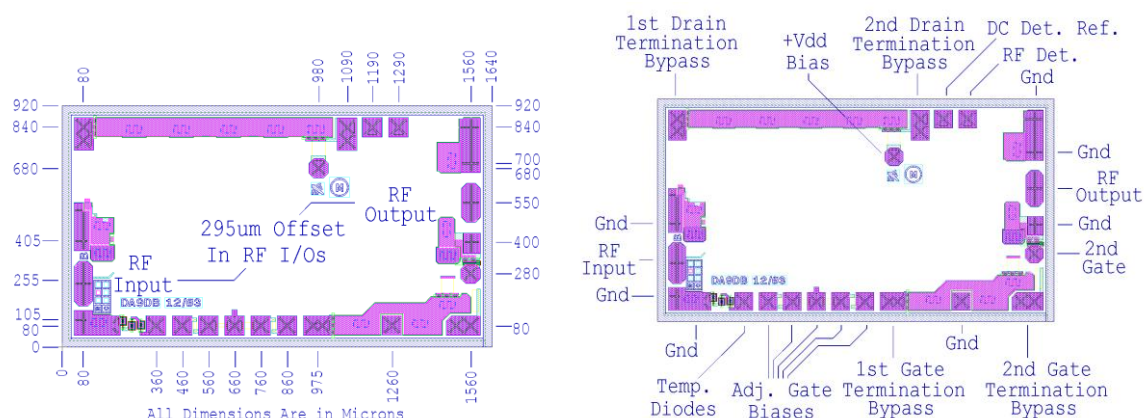


Figure 1. Die size, pad locations, and pad descriptions

Chip size: 1640x920 μ m (64.6x36.2mil)
 Chip size tolerance: ± 5 μ m (0.2mil)
 Chip thickness: 100 ± 10 μ m (4 ± 0.4 mil)
 Pad dimensions: 80x80 μ m (3.1x3.1mil)

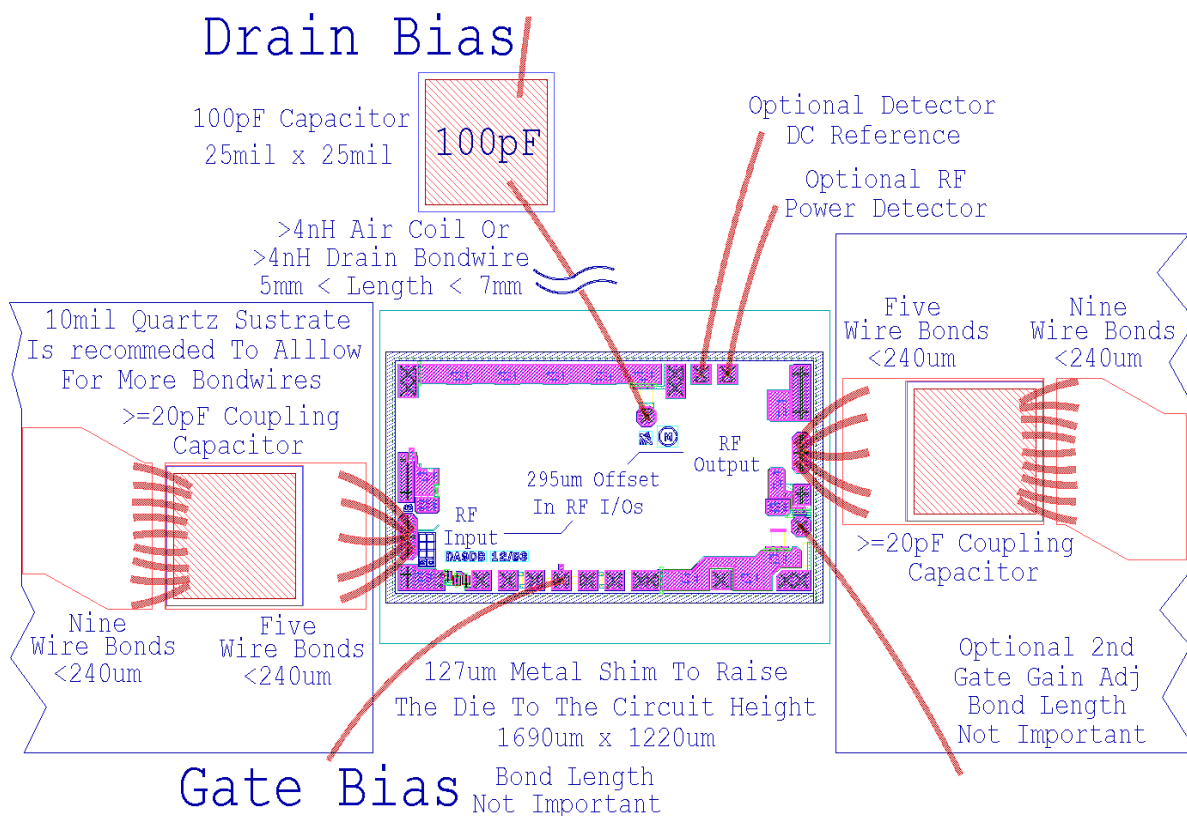


Figure 2.2 -65GHz bonding diagram

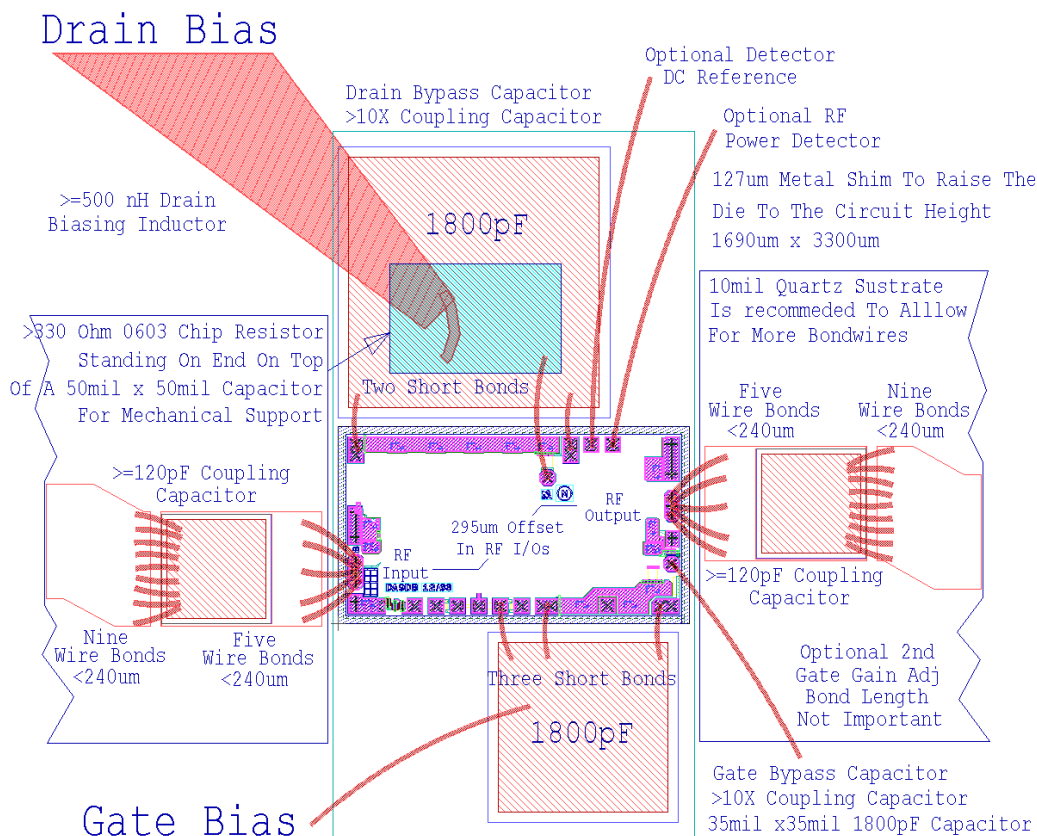


Figure 3. 40MHz-65GHz bonding diagram

Pick-up and Chip Handling

This MMIC has exposed air bridges on the top surface. **Do not pick up chip with vacuum on the die center**; handle from edges or use a collet.

Thermal Heat Sinking

To avoid damage and for optimum performance, you must observe the maximum channel temperature and ensure adequate heat sinking.

ESD Handling and Bonding

This MMIC is ESD sensitive; preventive measures should be taken during handling, die attach, and bonding.

Epoxy die attach is recommended. Please review our application note [MM-APP-0001 GaAs MMIC handling and die attach recommendations](#), on our website for more handling, die attach and bonding information.



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